Product Change Notification - JAON-23UZTC781

Date:	24 Nov 2017
Product Category:	Touchscreen Controllers; 32-bit PIC Microcontrollers
Notification subject:	CCB 3130 Initial Notice: Qualification of ASCL as an additional bumping facility for selected Atmel
	products available in 20L, 35L, 36L, 45L, 49L and 64L WLSCP package.
Notification text:	PCN Status: Initial notification
	PCN Type: Manufacturing Change
	Microchip Parts Affected: Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.
	NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).
	Description of Change: Qualification of ASCL as an additional bumping facility for selected Atmel products available in 20L, 35L, 36L, 45L, 49L and 64L WLSCP package.
	Pre Change:
	Bumping facility at ASE site.
	Post Change:

Bumping facility at ASE or ASCL site.

Pre and Post Change Summary:

	Pre Change	hange	
Bumping facility / Assembly Site	ASE Inc (ASEK)	ASEK	ASE Group Chung-Li (ASCL)
RDL material	Ti/Al/Ti	Ti/Al/Ti	Ti/Al/Ti
UBM composition	Al/NiV/Cu	Al/NiV/Cu	Al/NiV/Cu
PBO material	HD8820	HD8820 HD8	

Impacts to Data Sheet: None

Change Impact: None

Reason for Change: To improve cycle time by qualifying ASCL as an additional bumping facility.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: June 2018 Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	November 2017			->	June 2018						
Workweek	44	45	46	47			22	23	24	25	26
Initial PCN Issue Date				х							
Qual Report Availability									х		
Final PCN Issue Date									х		

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

November 24, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_JAON-23UZTC781_Affected CPN.pdf PCN_JAON-23UZTC781_Qual_Plan.pdf PCN_JAON-23UZTC781_Affected CPN.xls

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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If you wish to change your product/process change notification (PCN) profile please log on to our website at http://www.microchip.com/PCN sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to microchipDIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

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Affected Catalog Part Numbers (CPN)

PCN_JAON-23UZTC781
CATALOG_PART_NBR
ATMXT144U-UUR028
ATSAMD10D14A-UUT
ATSAMD10D14A-UUTB5
ATSAMD10D14A-UUTBN
ATSAMD11D14A-UUT
ATSAMD20G17A-UUT
ATSAMD20G18A-UNT
ATSAMD20G18A-UUT
ATSAMD21E15C-UUT
ATSAMD21E16C-UUT
ATSAMD21E16C-UUTB4
ATSAML21J17B-UUT
ATSAML21J18B-UUT
ATSAML22G17A-UUT
ATSAML22G17A-UUTA0
ATSAML22G17A-UUTA1
ATSAML22G18A-UUT